

# GBU15A THRU GBU15M

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# GBU15A THRU GBU15M

## 15.0A Glass Passivated Single-Phase Bridge Rectifiers-50-1000V

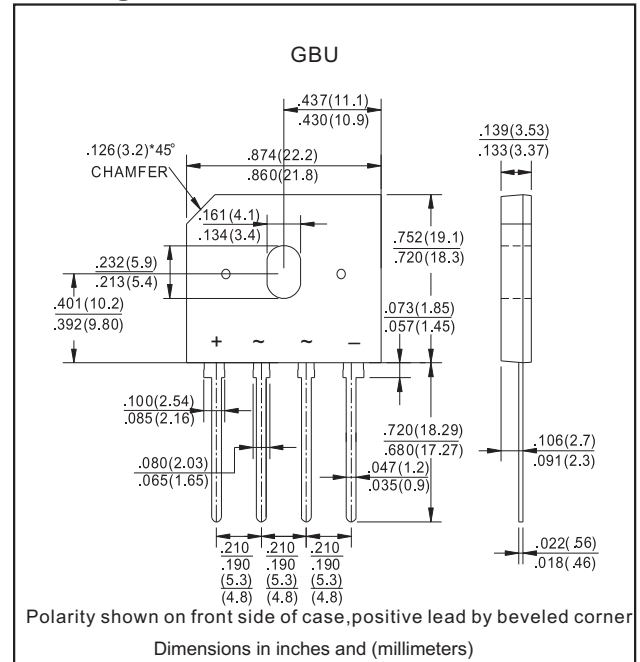
### Features

- Surge overload ratings to 240 amperes peak.
- Recommended for non-automatic applications.
- Ideal for & save space on printed circuit board.
- Applicable for automatic insertion.
- Reliable low cost construction utilizing molded plastic technology results in inexpensive product.
- Glass passivated chip junctions.
- Lead-free parts meet RoHS requirements.
- Suffix "-H" indicates Halogen free parts, ex. GBU15A-H.

### Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, GBU
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : marked on body
- Mounting Position : Any
- Weight : Approximated 4.00 gram

### Package outline



### Maximum ratings and Electrical characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

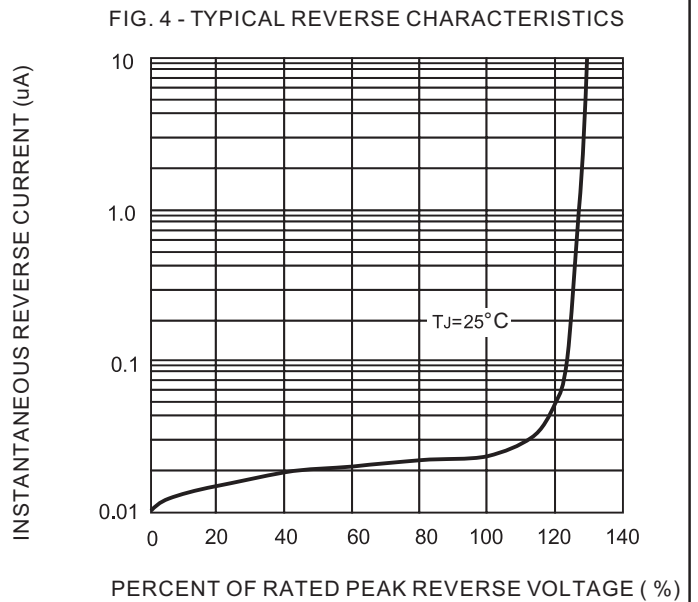
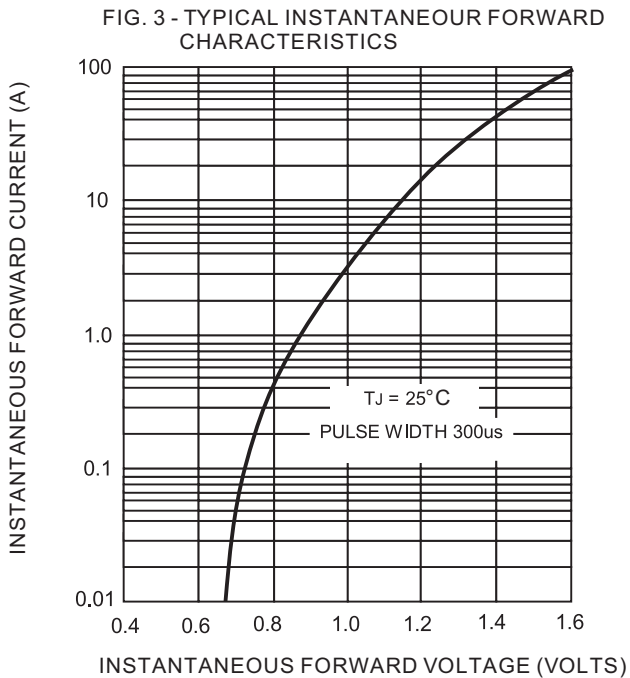
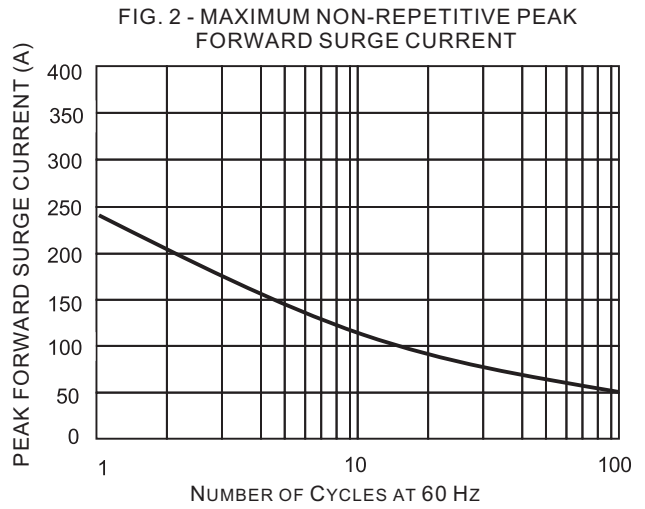
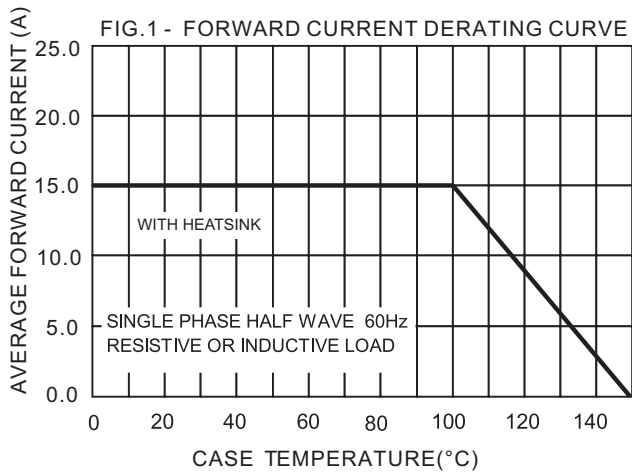
PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	(with heatsink Note 1) at $T_c=100^{\circ}\text{C}$ (without heatsink)	$I_o$			15.0 3.2	A
Forward surge current	8.3ms single half sine-wave (JEDEC methode)	$I_{FSM}$			240	A
Reverse current	$V_R = V_{RRM} T_J = 25^{\circ}\text{C}$	$I_R$			10.0	uA
	$V_R = V_{RRM} T_J = 125^{\circ}\text{C}$				500	
$I^2t$ Rating for fusing	$t < 8.3$ ms	$I^2t$			239	$\text{A}^2\text{s}$
Typical junction capacitance per element	Measured at 1.0MHz and applied reverse voltage of 4.0 VDC	$C_J$		70		pF
Typical thermal resistance	Junction to case	$R_{\theta JC}$		2.2		$^{\circ}\text{C}/\text{W}$
Storage temperature		$T_{STG}$	-65		+175	$^{\circ}\text{C}$

Note 1. Device mounted on 100mm\*100mm\*1.6mm Cu plate heatsink.

SYMBOLS	$V_{RRM}^{*1}$ (V)	$V_{RMS}^{*2}$ (V)	$V_R^{*3}$ (V)	$V_F^{*4}$ (V)	Operating temperature $T_J, (^{\circ}\text{C})$
GBU15A	50	35	50	1.10	-55 to +150
GBU15B	100	70	100		
GBU15D	200	140	200		
GBU15G	400	280	400		
GBU15J	600	420	600		
GBU15K	800	560	800		
GBU15M	1000	700	1000		

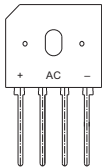
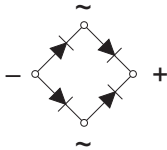
- \*1 Repetitive peak reverse voltage
- \*2 RMS voltage
- \*3 Continuous reverse voltage
- \*4 Maximum forward voltage@ $I_F=7.5\text{A}$

## Rating and characteristic curves (GBU15A THRU GBU15M)



# GBU15A THRU GBU15M

## Pinning information

Simplified outline	Symbol
	

## Marking

Type number	Marking code
GBU15A	GBU15A
GBU15B	GBU15B
GBU15D	GBU15D
GBU15G	GBU15G
GBU15J	GBU15J
GBU15K	GBU15K
GBU15M	GBU15M

## Tube packing

PACKAGE	TUBE (pcs)	TUBE SIZE (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
GBU	20	474*42*7	496*225*90	1,000	6.5

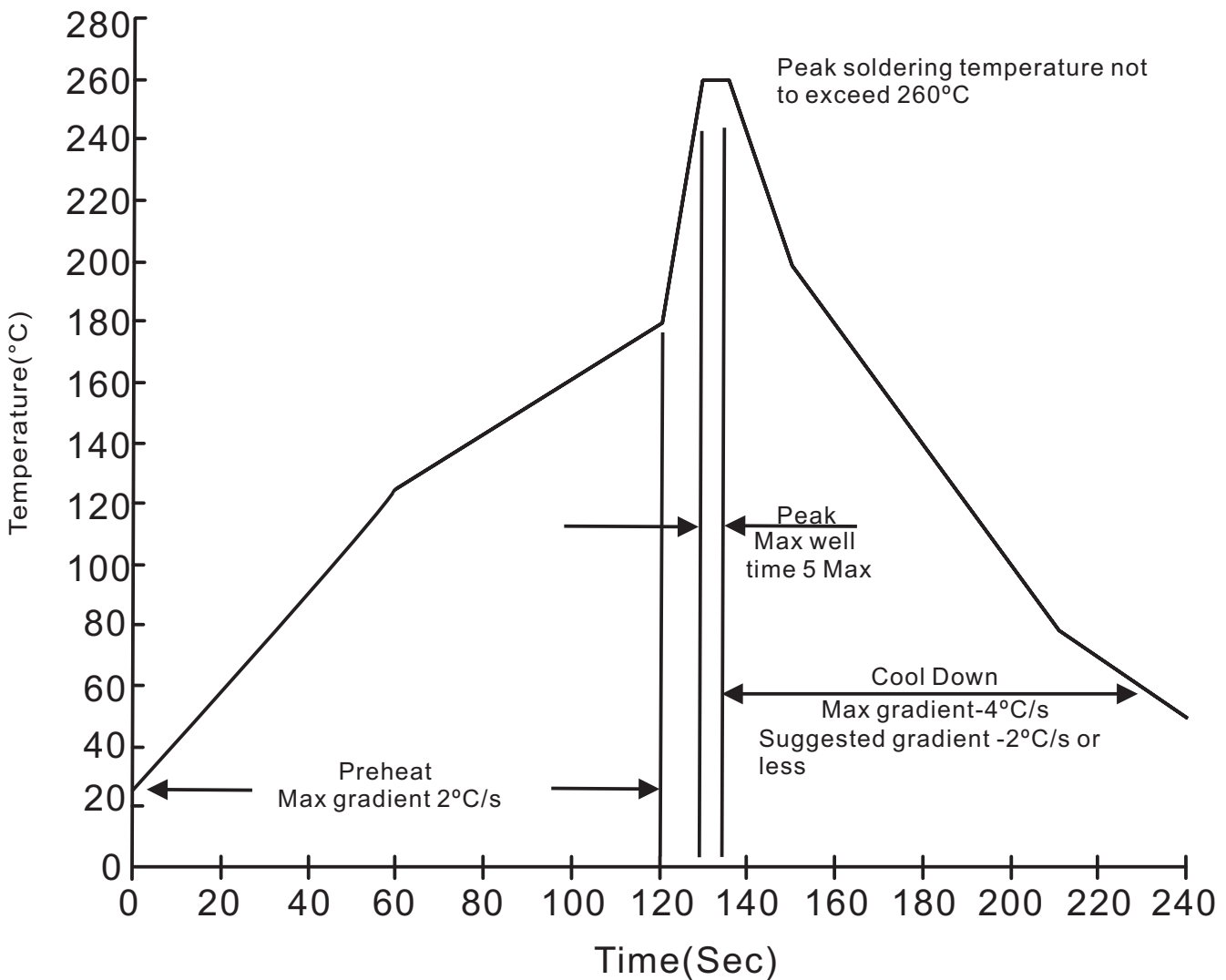
## BULK PACKING

DEVICE CASE TYPE	Q'TY 1 (PCS / BOX)	INNER BOX SIZE (m/m)	CARTON SIZE (m/m)	Q'TY 2 (PCS / CARTON)	APPROX. CROSS WEIGHT(kg)
GBU	800	350 * 337 * 44	375 * 360 * 213	3,200	16.9

# GBU15A THRU GBU15M

## Suggested thermal profiles for soldering processes

### 1. Lead free temperature profile wave-soldering



# GBU15A THRU GBU15M

## High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at 260±5°C for 10±2sec. immerse body into solder 1/16"±1/32"	MIL-STD-750D METHOD-2031
2. Solderability	at 245±5°C for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R=80\%$ rate at $T_J=150^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A=25^\circ\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^\circ\text{C}$ , $I_F = I_o$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A=121^\circ\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8 Forward Surge	8.3ms single half sine-wave , one surge.	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A=85^\circ\text{C}$ , RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031